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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

## **CONVEYING PARTY DATA**

Name	Execution Date
Hiroshi ISHIDA	08/08/2008
Atsushi MAEDA	08/26/2008
Minoru ABIKO	08/21/2008
Takehiko KIJIMA	08/21/2008
Takashi TAKEUCHI	08/18/2008
Shoji YOSHIDA	08/08/2008
Natsuo YAMAGUCHI	08/21/2008
Yasuhiro KIMURA	08/28/2008
Tetsuya UCHIDA	08/28/2008
Norio ISHITSUKA	08/25/2008

## **RECEIVING PARTY DATA**

Name:	Renesas Technology Corp.	
Street Address: 6-2, Otemachi 2-chome, Chiyoda-ku		
City:	Tokyo	
State/Country: JAPAN		

# PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	12262180	

#### **CORRESPONDENCE DATA**

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PATENT

500696096 REEL: 021790 FRAME: 0952

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ATTORNEY DOCKET NUMBER:	XA-11183(T3844-15666US01)	
NAME OF SUBMITTER:	Mitchell W. Shapiro	
Total Attachments: 1 source=assignment#page1.tif		

PATENT REEL: 021790 FRAME: 0953

# **ASSIGNMENT**

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Renesas Technology Corp., a corporation organized under the laws of Japan.

located at 6-2, Otemachi 2-chome, Chiyoda-ku, Tokyo, Japan,

receipt of which is hereby acknowledged I do hereby sell and assign to said Renesas Technology Corp., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

#### A SEMICONDUCTOR DEVICE AND A METHOD OF MANUFACTURING THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Renesas Technology Corp.,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Renesas Technology Corp.

Signed on the date(s) indicated aside our signatures:

RECORDED: 11/05/2008

#### INVENTOR(S) (発明者フルネームサイン)

Date Signed (署名日)

1)	Hinshi Ishida	Hiroshi ISHIDA	8/August /2008
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3)	Minora Abiko	Minoru ABIKO	21/August /2008
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5)	Takashi Takeudhi	Takashi TAKEUCHI	18/August/2008
6)	Shoji Yoshida	Shoji YOSHIDA	8/August/2008
7)_	Natsuo Yamaguchi	Natsuo YAMAGUCHI	21/August/2008
8)_	Yasuhiro Kimura	Yasuhiro KIMURA	28/August / 2008
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